

Description

The VSM90N08 uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. This device is suitable for use in PWM, load switching and general purpose applications.

General Features

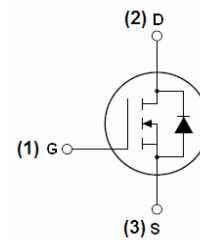
- $V_{DS} = 82V, I_D = 90A$
 $R_{DS(ON)} < 12 m\Omega @ V_{GS} = 10V$ (Typ: 9mΩ)
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Special designed for convertors and power controls
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

- Power switching application
- Hard switched and High frequency circuits
- Uninterruptible power supply



TO-220C



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VSM90N08-TC	VSM90N08	TO-220C	-	-	-

Absolute Maximum Ratings ($T_A = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	82	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	90	A
Drain Current-Continuous($T_C = 100^\circ C$)	$I_D (100^\circ C)$	63.6	A
Pulsed Drain Current	I_{DM}	320	A
Maximum Power Dissipation	P_D	130	W
Derating factor		0.87	W/ $^\circ C$
Single pulse avalanche energy ^(Note 5)	E_{AS}	380	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 175	$^\circ C$

Thermal Characteristic

Thermal Resistance, Junction-to-Case ^(Note 2)	$R_{\theta JC}$	1.15	$^{\circ}\text{C/W}$
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Electrical Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

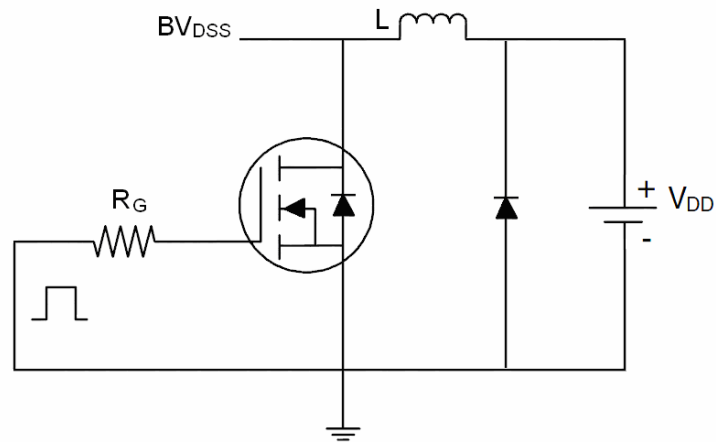
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	82	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =82V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics ^(Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250μA	2	3	4	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =20A	-	9	12	mΩ
Forward Transconductance	g _{FS}	V _{DS} =5V,I _D =20A	-	30	-	S
Dynamic Characteristics ^(Note4)						
Input Capacitance	C _{iss}	V _{DS} =25V,V _{GS} =0V, F=1.0MHz	-	4414	-	PF
Output Capacitance	C _{oss}		-	219	-	PF
Reverse Transfer Capacitance	C _{rss}		-	188	-	PF
Switching Characteristics ^(Note 4)						
Turn-on Delay Time	t _{d(on)}	V _{DD} =40V,R _L =15Ω R _G =2.5Ω,V _{GS} =10V	-	19	-	nS
Turn-on Rise Time	t _r		-	12	-	nS
Turn-Off Delay Time	t _{d(off)}		-	40	-	nS
Turn-Off Fall Time	t _f		-	15	-	nS
Total Gate Charge	Q _g	V _{DS} =40V,I _D =20A, V _{GS} =10V	-	81.5	-	nC
Gate-Source Charge	Q _{gs}		-	26.9	-	nC
Gate-Drain Charge	Q _{gd}		-	23.7	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage ^(Note 3)	V _{SD}	V _{GS} =0V,I _S =20A	-	-	1.2	V
Diode Forward Current ^(Note 2)	I _S		-	-	90	A
Reverse Recovery Time	t _{rr}	T _j =25℃,I _F =20A di/dt=100A/μs ^(Note3)	-	36	-	nS
Reverse Recovery Charge	Q _{rr}		-	54	-	nC

Notes:

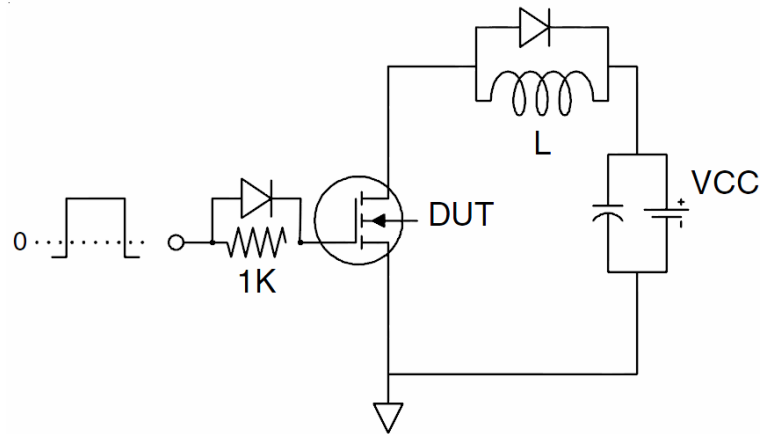
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production
5. EAS condition: $T_J=25^{\circ}\text{C}, V_{DD}=40V, V_G=10V, L=0.5mH, R_G=25\Omega$

Test Circuit

1) E_{AS} Test Circuits



2) Gate Charge Test Circuit



3) Switch Time Test Circuit



Typical Electrical and Thermal Characteristics (Curves)

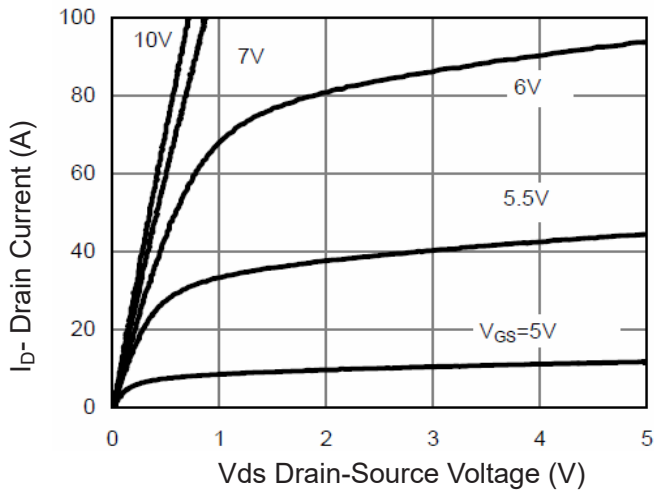


Figure 1 Output Characteristics

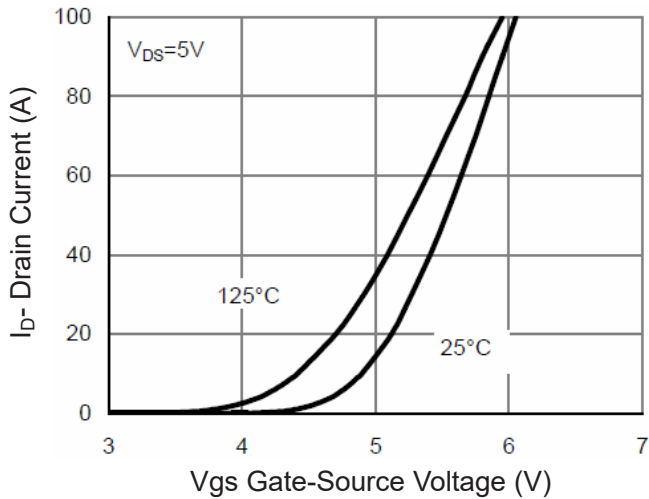


Figure 2 Transfer Characteristics

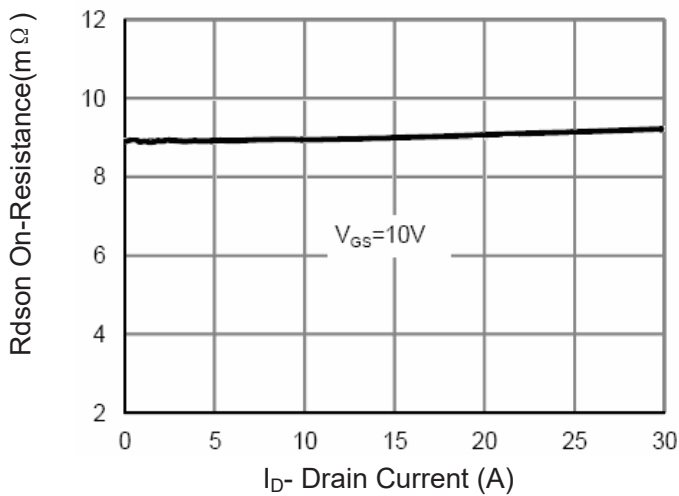


Figure 3 Rdson- Drain Current

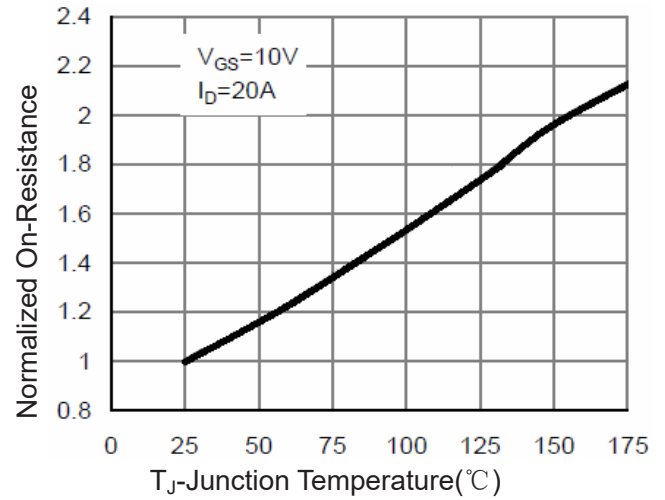


Figure 4 Rdson-Junction Temperature

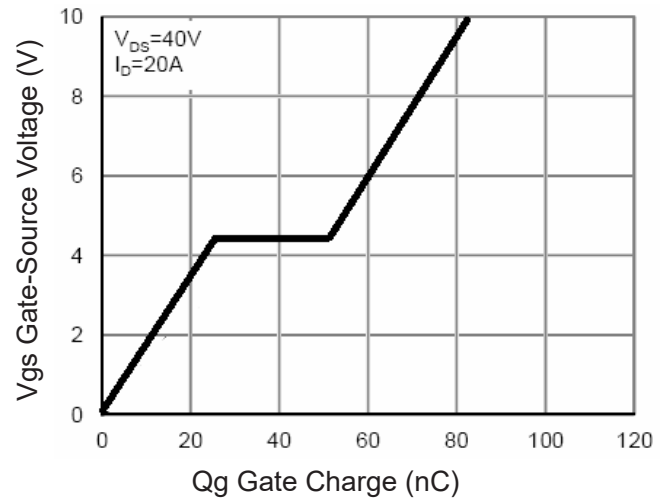


Figure 5 Gate Charge

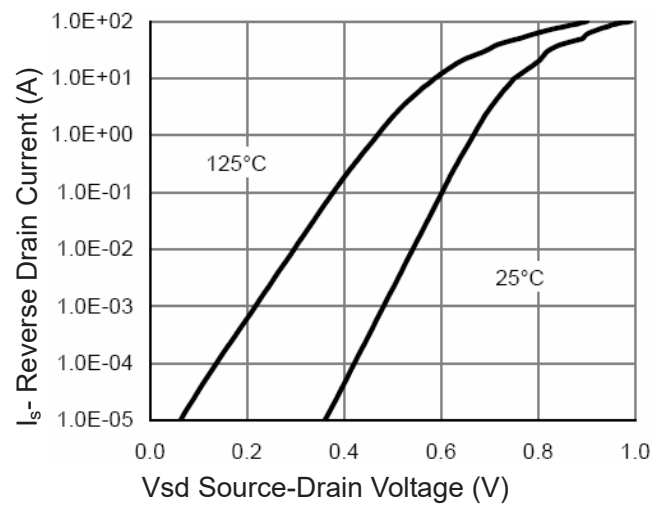
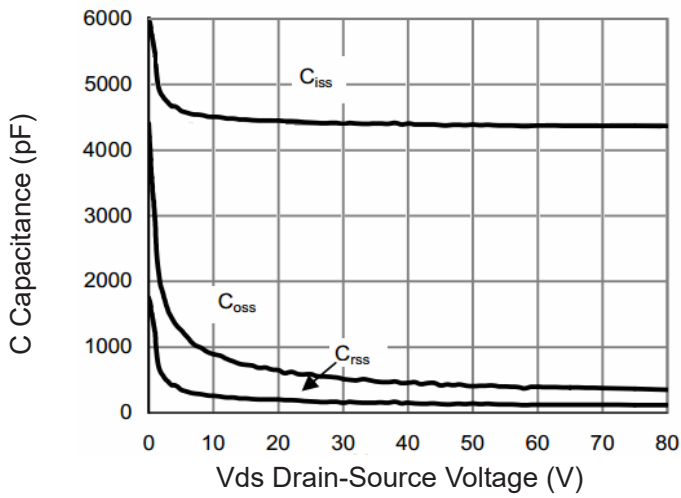
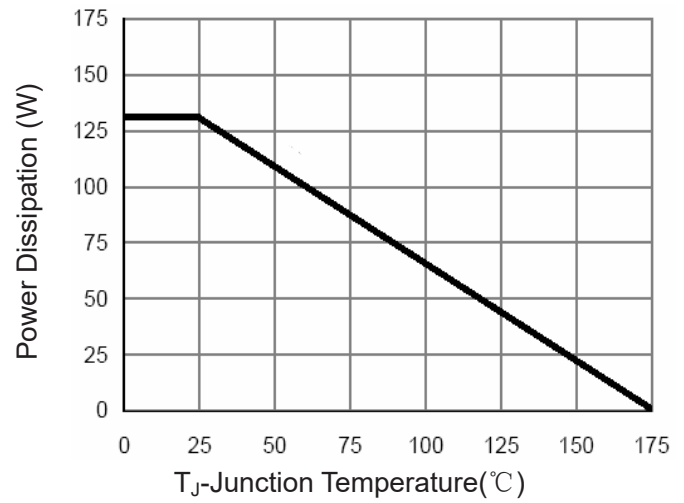
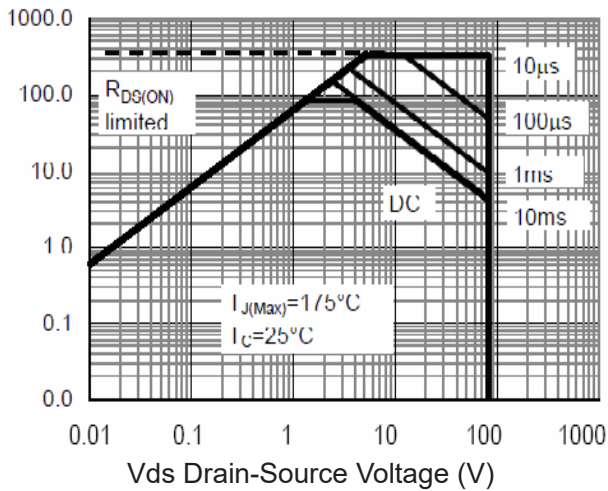
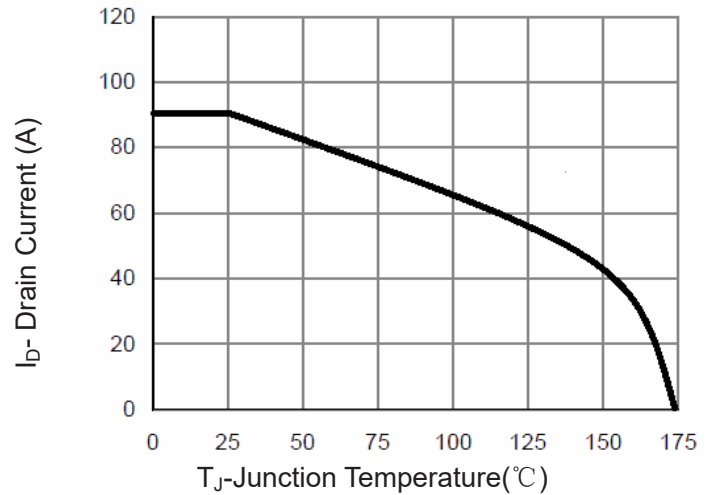
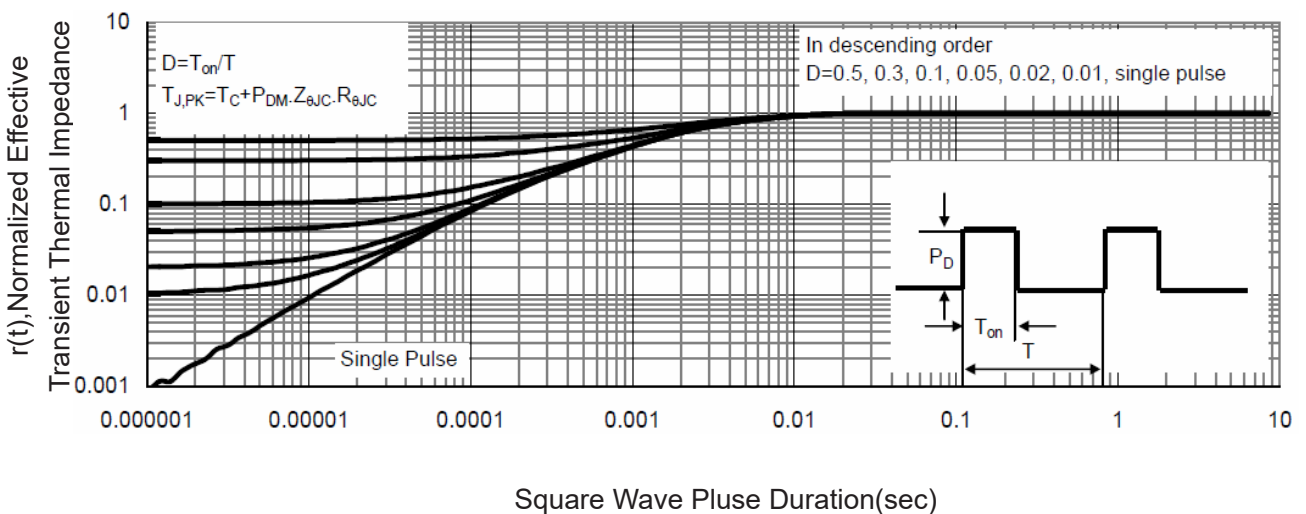


Figure 6 Source- Drain Diode Forward


Figure 7 Capacitance vs Vds

Figure 9 Power De-rating

Figure 8 Safe Operation Area

Figure 10 I_D Current De-rating

Figure 11 Normalized Maximum Transient Thermal Impedance